

## 3D Detector Testing

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Detectors with a “double sided”3D configuration have been fabricated at CNM, where the n- and p-type columns are etched from opposite sides of the wafer and do not pass through the full substrate thickness. Strip detectors have been wire bonded to Beetle analogue front-end read-out chips. Pixel detectors have been bump-bonded to Medipix read-out chips at VTT. The initial results obtained from testing these devices in Glasgow are presented.

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